

cles in the PMZ appears to be initiated by the eutectic reaction $\alpha + \theta \rightarrow L_E$ at the eutectic temperature T_E , and intensified by further melting of the surrounding α phase above T_E .

Liquation at Grain Boundaries

Figures 3B and C show that, in the PMZ, GBs appear to be eutectic — divorced eutectic where the GB eutectic is thin and normal eutectic where it is thicker. In the former case, the α phase of the eutectic grows upon and is, therefore, indistinguishable from the primary α of the matrix, leaving θ alone visible at the GBs. In the latter, the GB eutectic shows the normal composite-like structure of ($\alpha + \theta$). The formation of GB eutectic is explained below.

As shown previously in Fig. 3A, small θ particles are present along GBs before welding. At the edge of the PMZ facing the base metal (Fig. 4B and D), the peak temperature during welding is T_E . Here, GB θ particles react eutectically with the surrounding α phase and form a thin liquid-eutectic GB film. Upon cooling, it solidifies as solid eutectic along GBs, as shown by the arrows in Fig. 4B and D. This GB eutectic is thin and hence more likely to be divorced than normal.

In the PMZ, however, the peak temperature during welding is above T_E . Here, the GBs are severely liquated, as shown in Fig. 4E. The GB eutectic appears to be mostly divorced, as mentioned previously (Fig. 3B and C). Adjacent to each GB is essentially a light-etching, eutectic-free strip of the α phase. Similar strips are, in fact, also present in Fig. 3B and C, except they do not look any lighter in color under the scanning electron microscope. The presence of an α strip along the GB is also evident in Fig. 4F. The reason for the presence of an α strip next to the GB eutectic is similar to that for the presence of the α phase surrounding the large eutectic particles within grains — Fig. 4E.

As already mentioned, when the peak temperature reaches the eutectic temperature T_E , the small θ particles along GBs react with the surrounding α phase and form a eutectic GB liquid. Referring again to the phase diagram in Fig. 1, when the peak temperature rises above T_E , the composition of the grain boundary liquid changes along the liquidus line from point e to, say, point f. Liquation intensifies as the fraction of the liquid rises significantly from $\overline{ad}/\overline{ae}$ to $\overline{bg}/\overline{bf}$. The large decrease in the Cu content of the GB liquid is achieved by melting the surrounding α phase of a much lower Cu content. Upon cooling, the hypoeutectic GB liquid solidifies initially as the α phase and

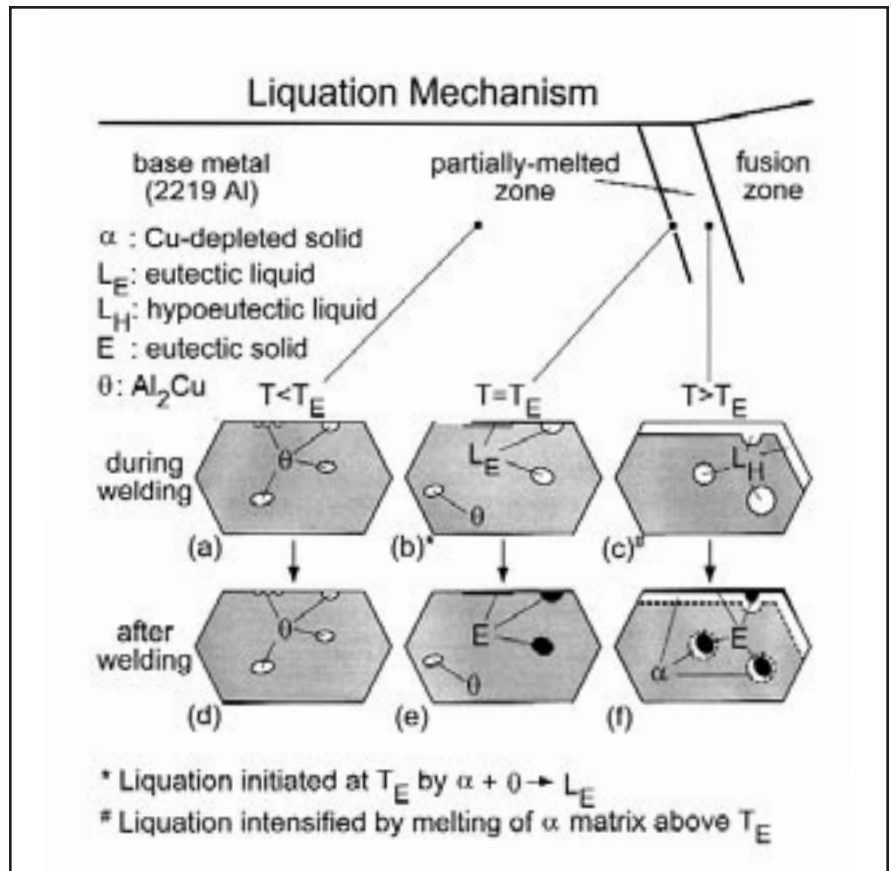


Fig. 5 — Schematic sketch showing the liquation mechanism in the partially melted zone.

finally as eutectic when T_E is reached. This explains why the GB eutectic is accompanied by a strip of the α phase.

One might suspect that Cu segregation to the GB by solid-state diffusion caused GB liquation. This liquation mechanism, however, raises the following questions. Why does Cu diffuse to the GB? Since the α strip appears on only one side of the GB (Figs. 3B, 3C, 4E and 4F), why does Cu diffuse to the GB from only one side? Furthermore, how can liquation within grains be explained?

Suppose within a narrow strip along the GB, Cu diffuses to the GB and causes it to melt. This solid-state diffusion leaves behind a Cu-depleted α strip along the GB (EPMA confirms Cu depletion in the α strip). Based on Figs. 3B, 3C, 4E and 4F, the α strips are about $10 \mu\text{m}$ (1×10^{-3} cm) wide. As an approximation, $x = Dt$, where x is the diffusion distance, D the diffusion coefficient and t the diffusion time. The diffusion coefficient for Cu in solid Al containing up to 3.5 wt-% Cu at around 600°C is about 1×10^{-8} cm^2/s (Refs. 14, 23). Based on these approximations, the time required for diffusion is 100 s. Obviously, this is far longer than the time the PMZ can possibly stay above

the eutectic temperature during welding. Therefore, Cu segregation is not expected to be the mechanism for GB liquation.

It should be emphasized the equilibrium partition coefficient, k , for Cu in Al-6.3%Cu alloy is less than unity. Approximately, $k = 5.65/33.2 = 0.170$. Consequently, as the GB liquid solidifies, Cu is rejected into the liquid to cause severe Cu segregation. According to the PMZ micrographs shown in Figs. 3B, 3C, 4E and 4F, the GB liquid solidifies with the planar solidification mode. Initially, the solid has a very low Cu concentration. As solidification proceeds, however, Cu continues to be rejected into the liquid ahead of the planar solidification front. Eventually, the liquid becomes eutectic and solidifies as the eutectic GB. This is why there is a light-etching, Cu-depleted α strip right next to the eutectic GB. This strip is wide because, as already mentioned, the fraction of the liquid in the PMZ increases significantly with increasing temperature, e.g., from $\overline{ad}/\overline{ae}$ at T_E to $\overline{bg}/\overline{bf}$ above T_E — Fig. 1. EPMA has confirmed severe Cu segregation from the α strip to the GB, as will be reported elsewhere.

The wide light-etching regions of Cu-

